ECE1388 VLSI Design Methodology

Lecture 15

Design for Testability

Adapted from Weste, Harris CMOS VLSI Design

Outline

- Testing
  - Logic Verification
  - Silicon Debug
  - Manufacturing Test
- Fault Models
- Observability and Controllability
- Design for Test
  - Scan
  - BIST
- Boundary Scan

Testing

- Testing is one of the most expensive parts of chips
  - Logic verification accounts for > 50% of design effort for many chips
  - Debug time after fabrication has enormous opportunity cost
  - Shipping defective parts can sink a company

- Example: Intel FDIV bug (1994)
  - Logic error not caught until > 1M units shipped
  - Recall cost $450M (!!!)

Logic Verification

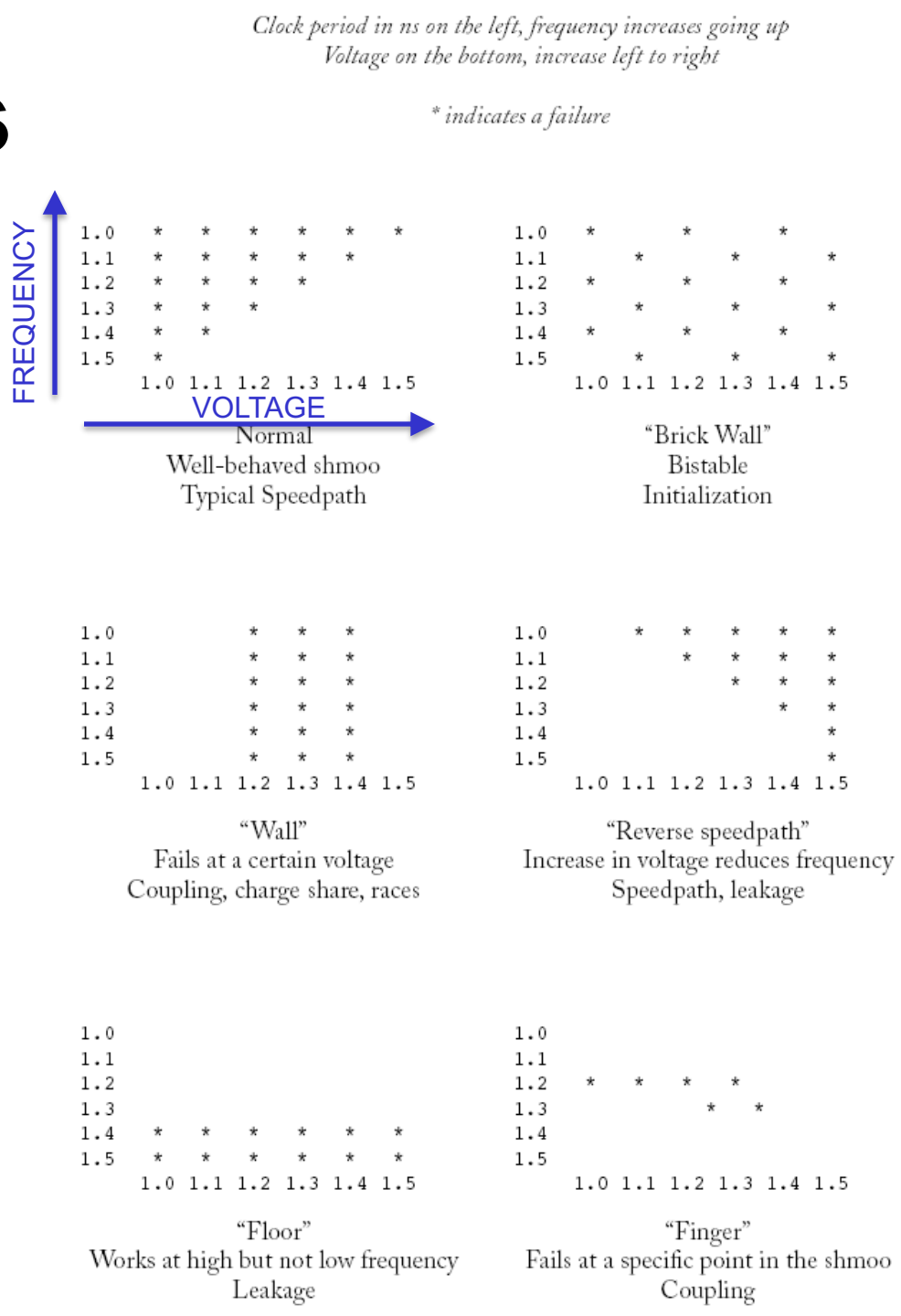
- Does the chip simulate correctly?
  - Usually done at HDL level
  - Verification engineers write test bench for HDL
    - Can't test all cases
    - Look for corner cases
    - Try to break logic design
- Ex: 32-bit adder
  - Test all combinations of corner cases as inputs:
    - 0, 1, 2, 2^{31}-1, -1, -2^{31}, a few random numbers
- Good tests require ingenuity

Silicon Debug

- Test the first chips back from fabrication
  - If you are lucky, they work the first time
  - If not…
- Logic bugs vs. electrical failures
  - Most chip failures are logic bugs from inadequate simulation
  - Some are electrical failures
    - Crosstalk
    - Dynamic nodes: leakage, charge sharing
    - Ratio failures
  - A few are tool or methodology failures (e.g. DRC)
- Fix the bugs and fabricate a corrected chip

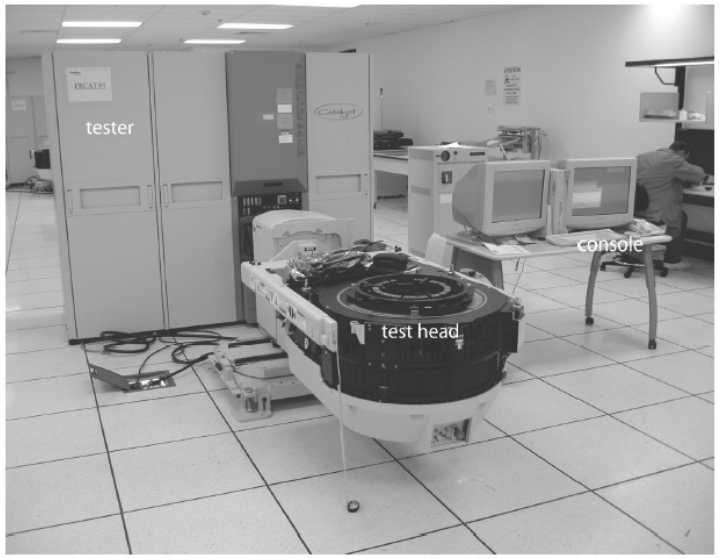
Shmoo Plots

- How to diagnose failures?
  - Hard to access chips
    - Picoprobes
    - Electron beam
    - Laser voltage probing
    - Built-in self-test
- Shmoo plots
  - Vary voltage, frequency
  - Look for cause of electrical failures

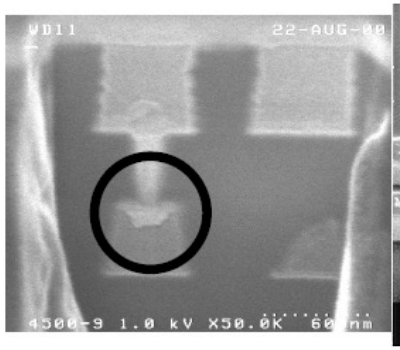


Manufacturing Test

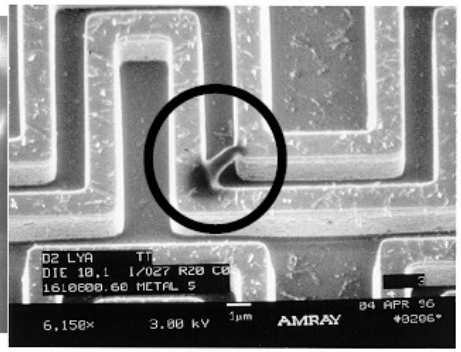
- A speck of dust on a wafer is sufficient to kill chip
- *Yield* of any chip is < 100%
  - Must test chips after manufacturing before delivery to customers to only ship good parts
- Manufacturing testers are very expensive
  - Minimize time on tester
  - Careful selection of *test vectors*



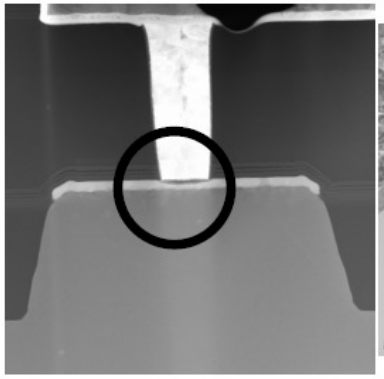
Manufacturing Failures



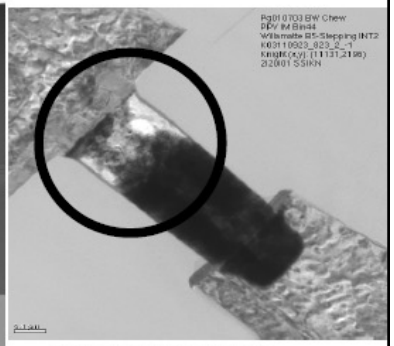
Metal 1 Shelving



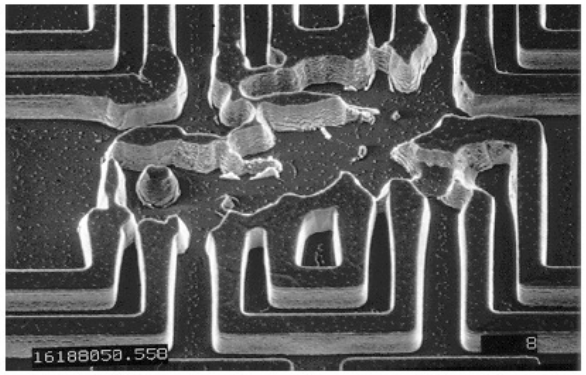
Metal 5 film particle
(bridging defect)



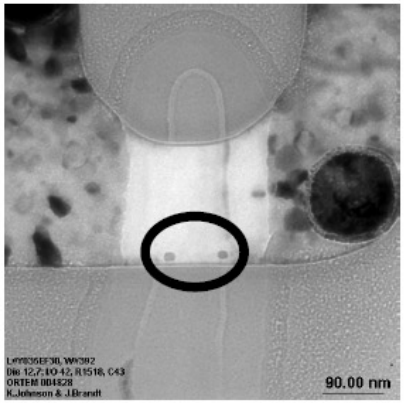
Open defect



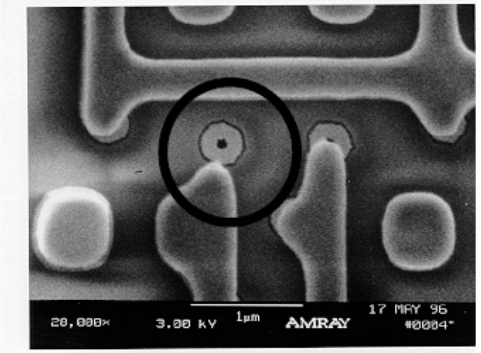
Spongy Via2
(Infant mortality)



Metal 5 blocked etch
(patterning defect)



Spot defects
"Co" Defect under Gate



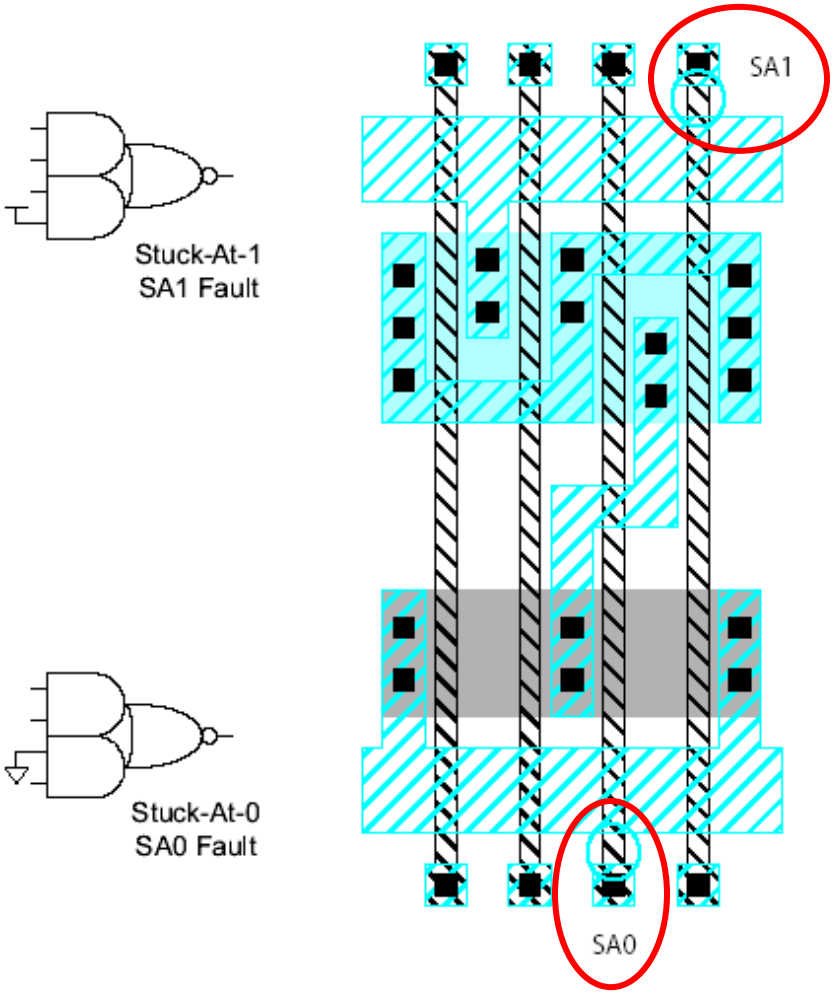
Metal 1 missing pattern
(open at contact)

SEM images courtesy Intel Corporation

Stuck-At Faults

- How does a chip fail?
  - Usually failures are shorts between two conductors or opens in a conductor
  - This can cause very complicated behavior
- A simpler model: *Stuck-At*
  - Assume all failures cause nodes to be "stuck-at" 0 or 1, i.e. shorted to GND or V_{DD}
  - Not quite true, but works well in practice

Examples



Observability & Controllability

- *Observability*: ease of observing a node by watching external output pins of the chip
- *Controllability*: ease of forcing a node to 0 or 1 by driving input pins of the chip

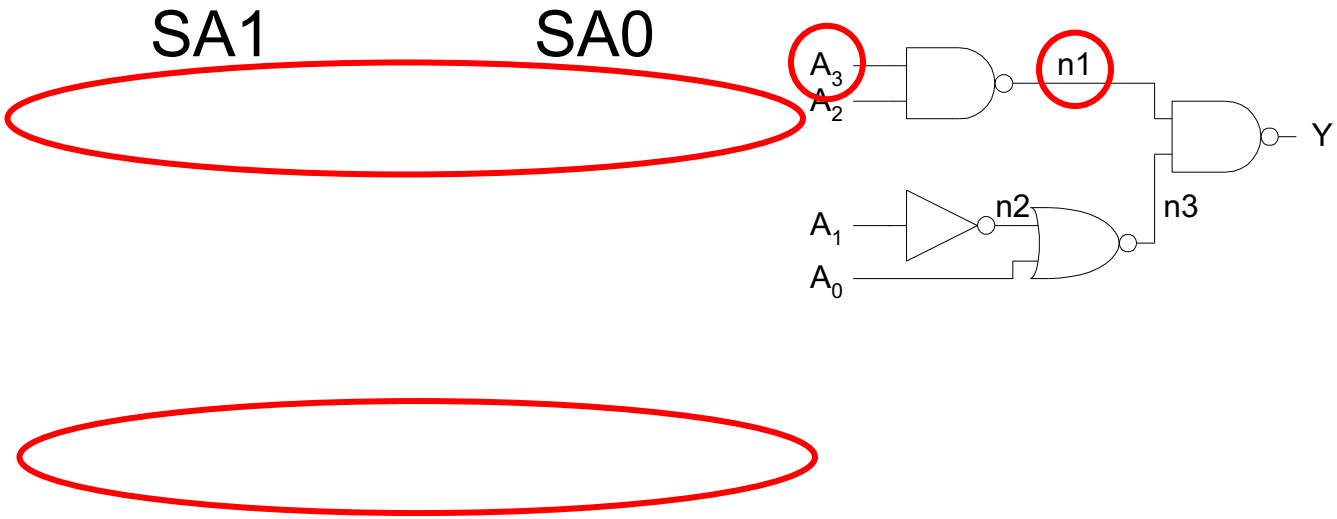
- Combinational logic is usually easy to observe and control
- Finite state machines can be very difficult, requiring many cycles to enter desired state
  - Especially if state transition diagram is not known to the test engineer

Test Pattern Generation

- Manufacturing test ideally would check every node in the circuit to prove it is not stuck
- Apply the smallest sequence of test vectors necessary to prove each node is not stuck

- Good observability and controllability reduces number of test vectors required for manufacturing test
  - Reduces the cost of testing
  - Motivates design-for-test

Test Example



- A_3
- A_2
- A_1
- A_0
- n1
- n2
- n3
- Y

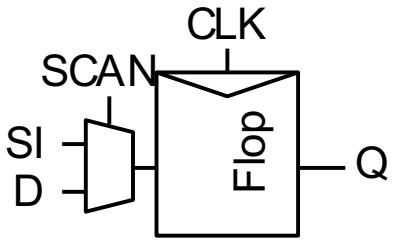
- Minimum set:

Design for Test

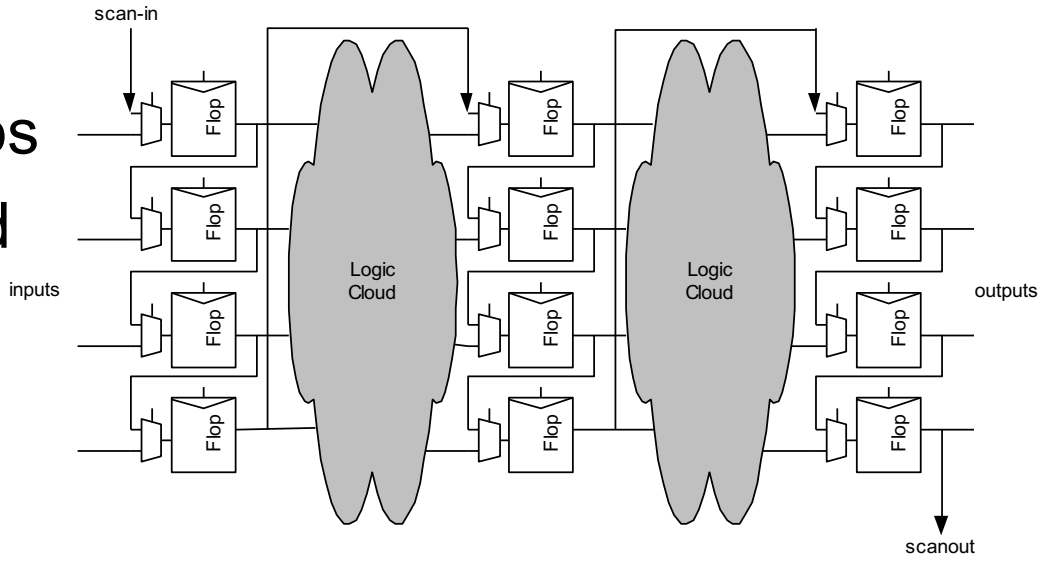
- Design the chip to increase observability and controllability
- If each register could be observed and controlled, test problem reduces to testing combinational logic between registers.
- Better yet, logic blocks could enter test mode where they generate test patterns and report the results automatically.

Scan

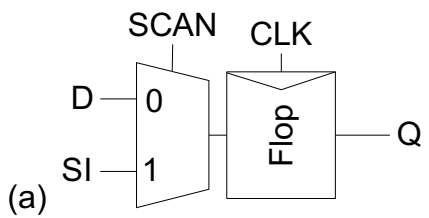
- Convert each flip-flop to a scan register
  - Only costs one extra multiplexer
- Normal mode: flip-flops behave as usual
- Scan mode: flip-flops behave as shift register

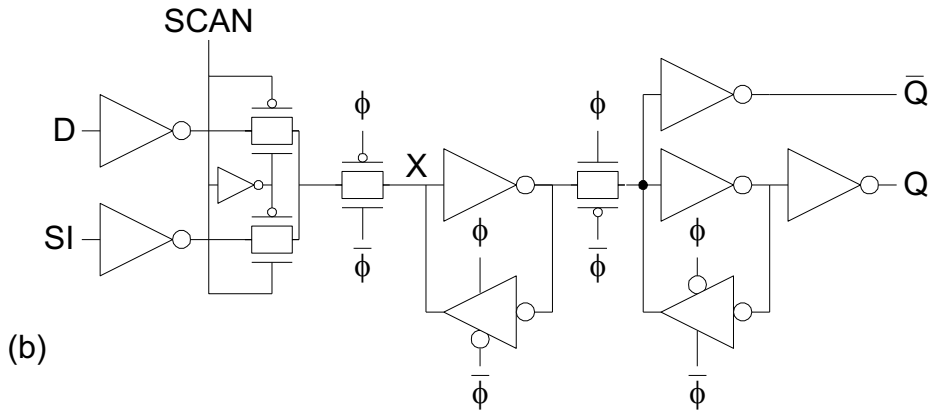


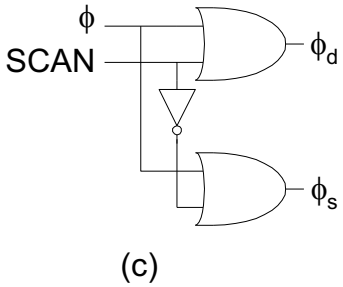
- Contents of flops can be scanned out and new values scanned in

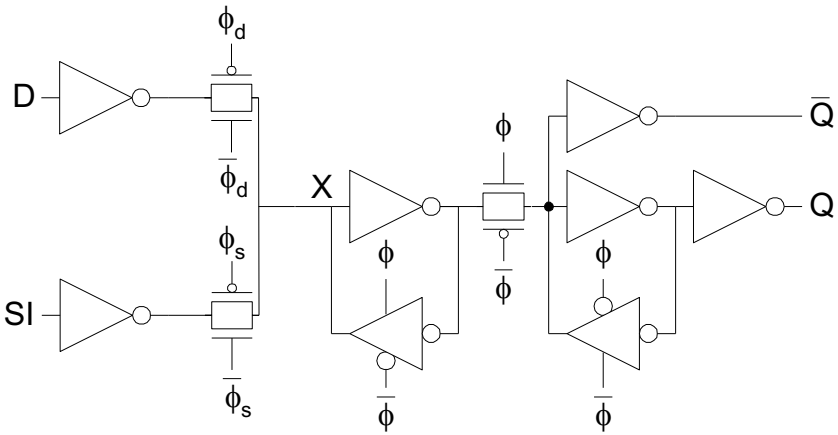


Scannable Flip-flops









ATPG

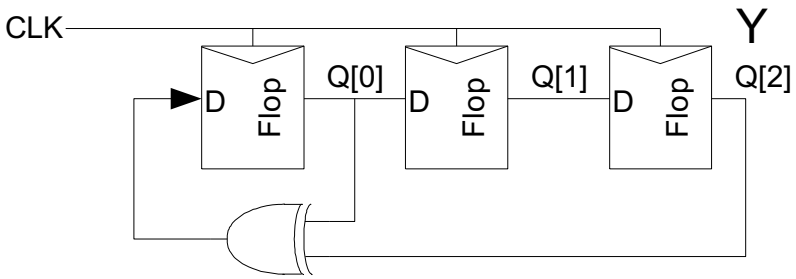
- Test pattern generation is tedious
- Automatic Test Pattern Generation (ATPG) tools produce a good set of vectors for each block of combinational logic
- Scan chains are used to control and observe the blocks
- Complete coverage requires a large number of vectors, raising the cost of test
- Most products settle for covering 90+% of potential stuck-at faults

Built-in Self-test

- Built-in self-test lets blocks test themselves
  - Generate pseudo-random inputs to comb. logic
  - Combine outputs into a *syndrome*
  - With high probability, block is fault-free if it produces the expected syndrome

PRSG

- *Linear Feedback Shift Register*
  - Shift register with input taken from XOR of state
  - *Pseudo-Random Sequence Generator*

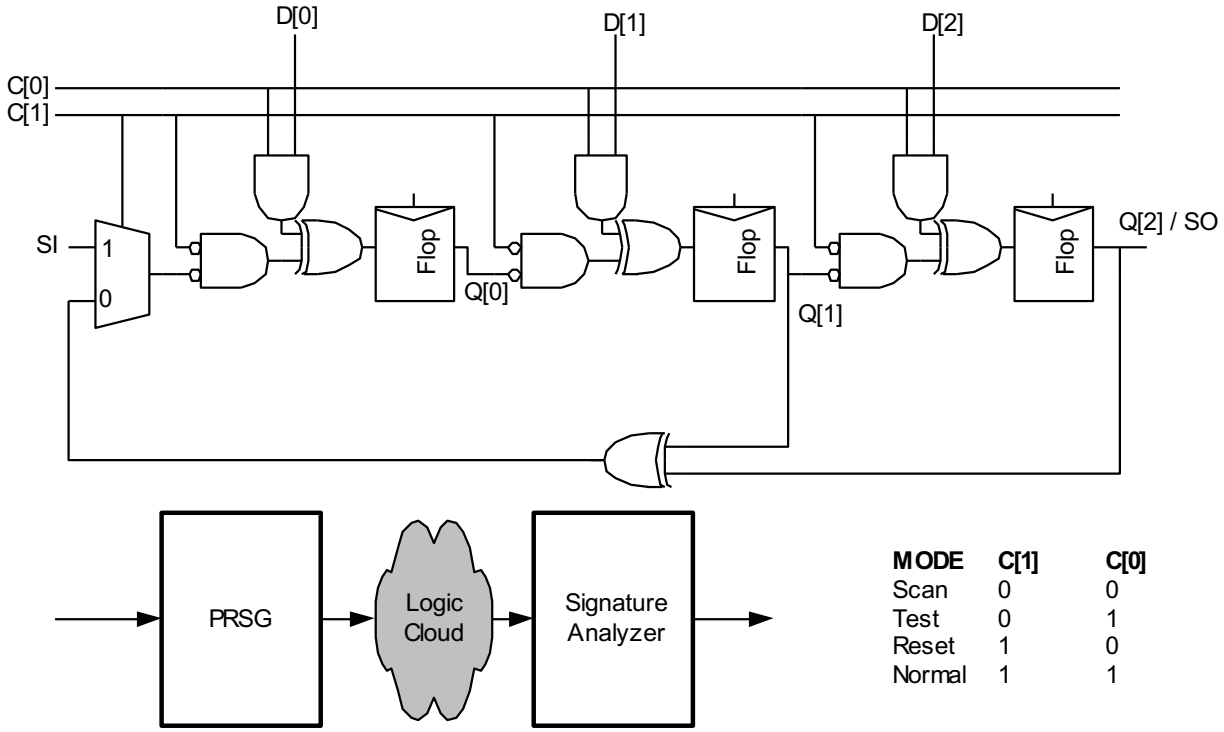


Flops reset to 111

Step	Y
0	
1	
2	
3	
4	
5	
6	
7	

BILBO

- Built-in Logic Block Observer
  - Combine scan with PRSG & signature analysis

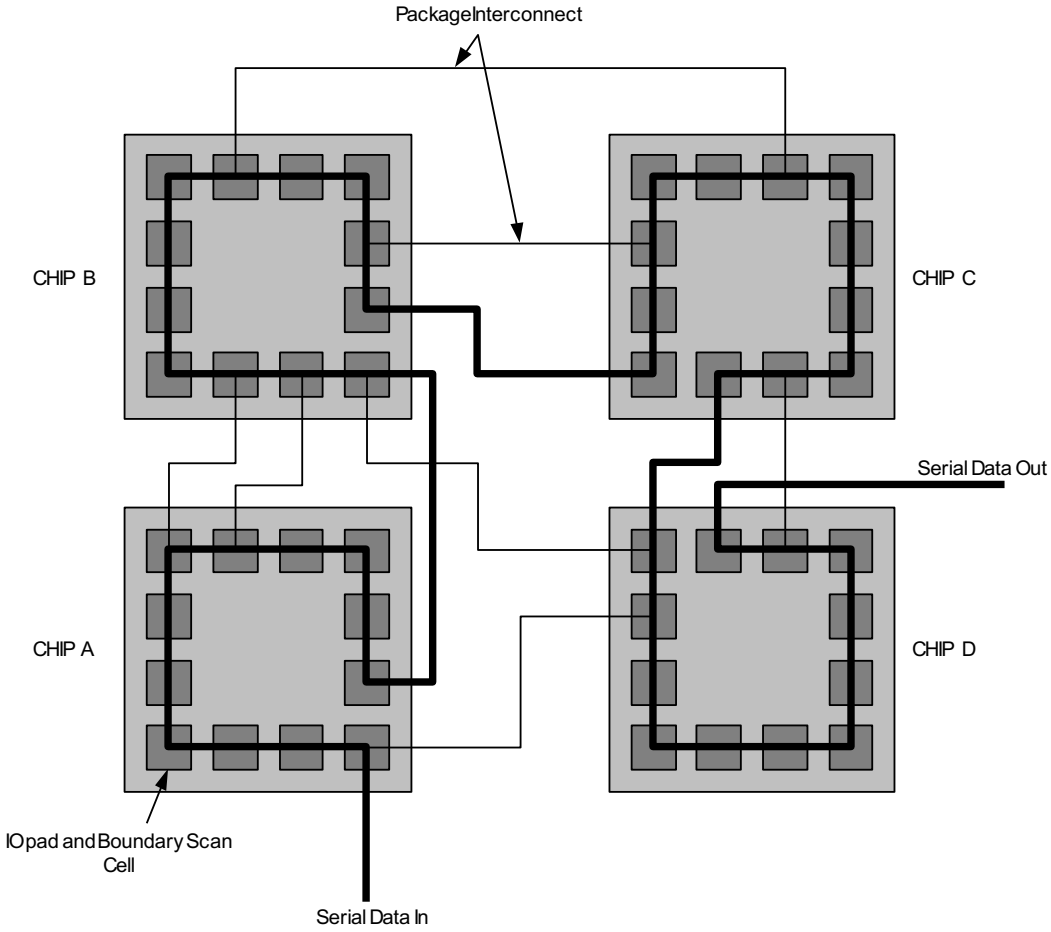


MODE	C[1]	C[0]
Scan	0	0
Test	0	1
Reset	1	0
Normal	1	1

Boundary Scan

- Testing boards is also difficult
  - Need to verify solder joints are good
    - Drive a pin to 0, then to 1
    - Check that all connected pins get the values
- Through-hole boards used “bed of nails”
- SMT and BGA boards cannot easily contact pins
- Build capability of observing and controlling pins into each chip to make board test easier

Boundary Scan Example



Boundary Scan Interface

- Boundary scan is accessed through five pins
  - TCK: test clock
  - TMS: test mode select
  - TDI: test data in
  - TDO: test data out
  - TRST*: test reset (optional)

- Chips with internal scan chains can access the chains through boundary scan for unified test strategy.

Testing Your Design

- Presilicon Verification
  - Test vectors: corner cases and random vectors
  - HDL simulation of schematics for functionality
  - Use 2-phase clocking to avoid races
  - Use static CMOS gates to avoid electrical failures
  - Use LVS to ensure layout matches schematic

- Postsilicon Verification
  - Run your test vectors on the fabricated chip
  - Use a functional chip tester
  - Potentially use breadboard or PCB for full system

Summary

- Think about testing from the beginning
  - Simulate as you go
  - Plan for test after fabrication

- "If you don't test it, it won't work! (Guaranteed)"